


MATERIAL DECLARATION SHEET



Material Number	ESD Suppressing Device CDNBS08 series			
Product Line	Semiconductor Products			
Compliance Date	2013/8/2			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.001500	Silicon	7440-21-3	100.00%	2.07%	2.07%
2	Lead frame	Copper Alloy	0.019872	Copper	7440-50-8	93.295%	27.412%	29.38%
			0.000533	Iron	7439-89-6	2.50%	0.734%	
			0.000021	Phosphorus	7723-14-0	0.10%	0.029%	
			0.000021	Zinc	7440-66-6	0.10%	0.029%	
			0.000852	Silver	7440-22-4	4%	1.175%	
3	Epoxy	Polymer	0.000550	Silicon dioxide Quartz	14808-60-7	55.00%	0.759%	1.379%
			0.000250	Epoxy resin	Proprietary	25.00%	0.345%	
			0.000030	Aromatic Amine	Proprietary	3.00%	0.041%	
			0.000170	Epoxy resin modifier	Proprietary	17.00%	0.234%	
4	Cu wire	Noble metal	0.000683	Copper	7440-50-8	97.50%	0.95%	0.97%
			0.000018	Palladium	7440-05-3	2.50%	0.02%	

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5	Mold Compound	Polymer	0.001380	Epoxy resin-1	Trade Secret	3.00%	1.90%	63.4407%
			0.001380	Epoxy resin-2	Trade Secret	3.00%	1.90%	
			0.001380	Epoxy resin-3	Trade Secret	3.00%	1.90%	
			0.001380	Phenol Resin	Trade Secret	3.00%	1.90%	
			0.000092	Carbon Black	1333-86-4	0.20%	0.13%	
			0.039468	Silica	60676-86-0	85.80%	54.4407%	
			0.000920	Crystalline Silica	14808-60-7	2.00%	1.27%	
6	Plating	plating	0.002000	Tin	7440-31-5	99.99%	2.76%	2.7603%
			0.0000002	Misc., not to declare	N/A	0.01%	0.0003%	
		Total weight	0.0725 g					

This Document was updated on: 2013/8/2

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.